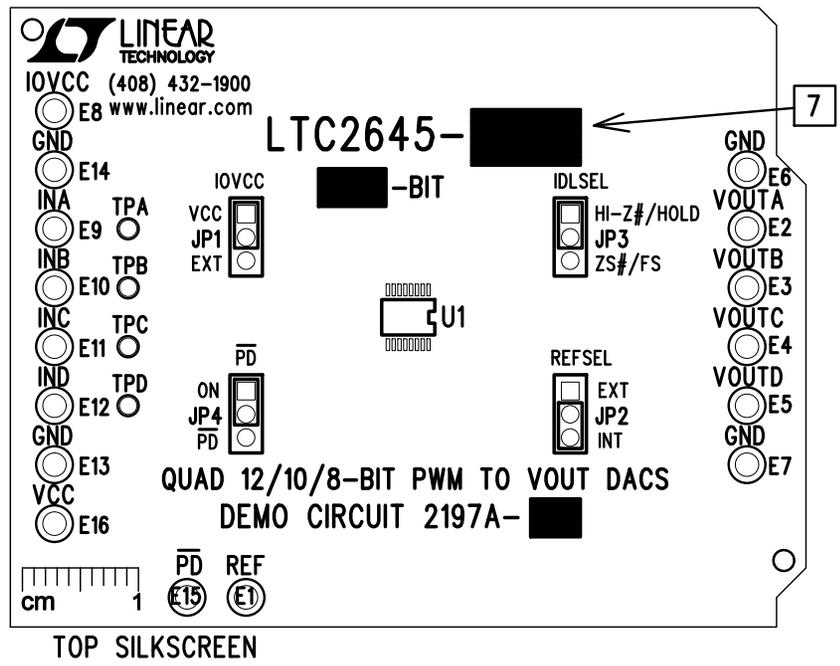


REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	1ST PROTOTYPE	MARK T.	02-07-14



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. MARK EACH SUFFIX, NUMBER OF BIT, AND ASSEMBLY TYPE IN THE WHITE BLOCK AREAS WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY	U1	SUFFIX	-BIT
A	LTC2645-L12	L12	12

APPROVALS			1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY	
PCB DES.	KIM T.		TITLE: TOP ASSEMBLY DRAWING	
APP ENG.	MARK T.	QUAD 12/10/8-BIT PWM TO VOUT DACS		
		SIZE	IC NO.	REV.
		N/A	LTC2645CMS FAMILY DEMO CIRCUIT 2197A	1
SCALE = NONE		FILENAME: DC2197A-1.PCB		SHT 1 OF 2